

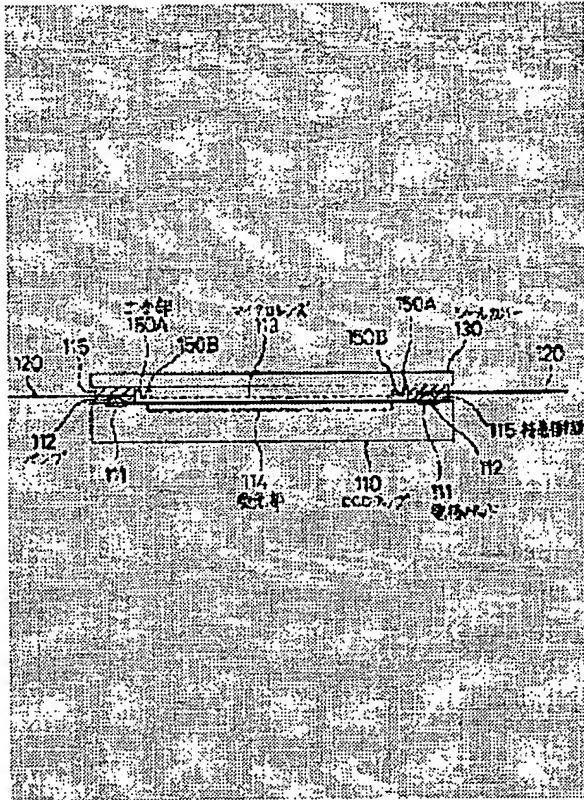
SOLID-STATE IMAGE PICKUP DEVICE

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Abstract of JP2003092394

PROBLEM TO BE SOLVED: To validly control the intrusion of adhesive resin to a light receiving part side, and to simplify reduction of the chip size. **SOLUTION:** A light receiving part 114 is formed at the central part of the upper face of a CCD chip 110, and adhesive resin 115 is arranged outside the light receiving part 114 so that the CCD chip 110 can be connected to a seal cover 130. Also, an on-chip micro-lens 113 is formed on the upper face of the light receiving part 114. Two bank parts 140A and 150B projected upward are formed at the outer peripheral part of the on-chip micro-lens 113. Those bank parts 150A and 150B are arranged across the whole periphery of the outer peripheral part of the on-chip micro-lens 113 almost like parallel lines, and integrally formed by being molded simultaneously when the on-chip micro-lens 113 is molded. Thus, the outside adhesive resin 115 can be prevented from intruding to the light receiving part 114 side by the bank parts 150A and 150B.



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